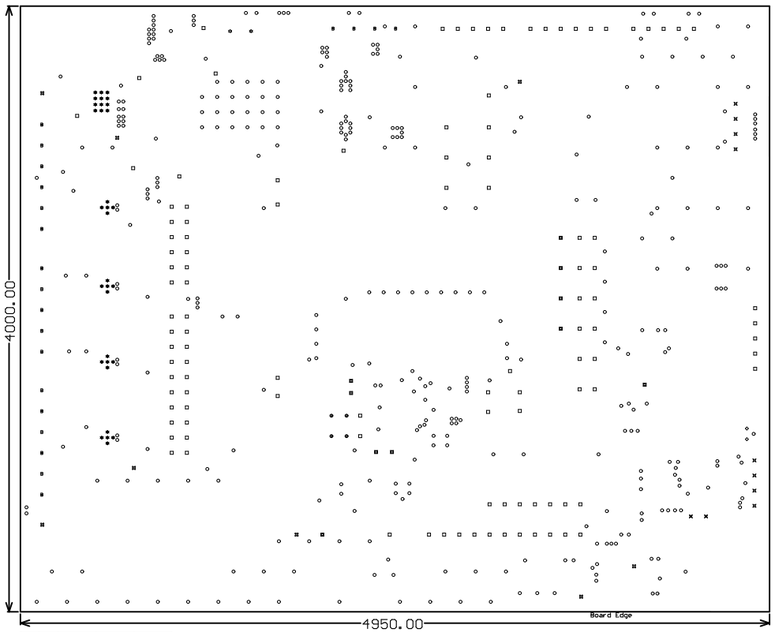
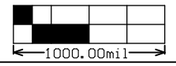
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Layer 1 - Top Layer	Copper	2.80mil		
	Dielectric 1	FR-4 High Tg	6.00mil	4.2	
2	Layer 2 - GND	Copper	1.40mil		
	Dielectric 2	FR-4 High Tg	41.00mil	4.2	
3	Layer 3 - Signal	Copper	1.40mil		
	Dielectric 3	FR-4 High Tg	6.00mil	4.2	
4	Layer 4 - Bottom Layer	Copper	2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				





Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
◇	2	31.50mil (0.800mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	Rounded
✖	2	45.28mil (1.150mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
✡	2	50.00mil (1.270mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
◎	4	35.00mil (0.889mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
✖	8	40.16mil (1.020mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
⊠	8	63.00mil (1.600mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	Rounded
◘	10	25.00mil (0.635mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	Rounded
B	21	43.31mil (1.100mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
✱	32	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Via	Rounded
□	109	40.00mil (1.016mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Pad	(Mixed)
○	376	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	Via	Rounded
	574 Total						

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____
☒ MATTE ☐ SEMI-GLOSS
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____
ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: BQ76952EVM
DESIGNED FOR: Public Release
FILE NAME: BMS029B.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BMS029	REV: B	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 6/30/2020 3:04:14 PM		TEXAS INSTRUMENTS

ENGINEER: M Sunna
LAYOUT BY: JMM Krypton solutions
SCALE: 1.00
ALTIUM DESIGNER VERSION: 19.1.9.167